

# LNJ312G8TRA

## Surface Mounting Chip LED

TSS Type

### ■ Absolute Maximum Ratings $T_a = 25^\circ\text{C}$

Parameter	Symbol	Rating	Unit
Power dissipation	$P_D$	50	mW
Forward current	$I_F$	20	mA
Pulse forward current *	$I_{FP}$	60	mA
Reverse voltage	$V_R$	4	V
Operating ambient temperature	$T_{opr}$	-30 to +85	$^\circ\text{C}$
Storage temperature	$T_{stg}$	-40 to +100	$^\circ\text{C}$

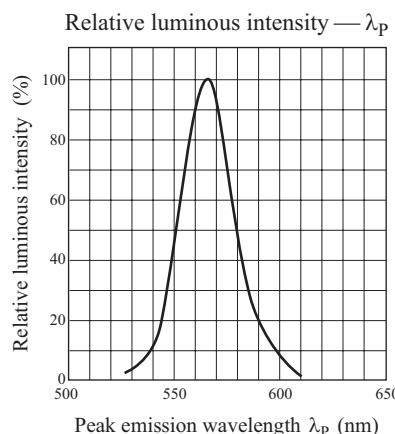
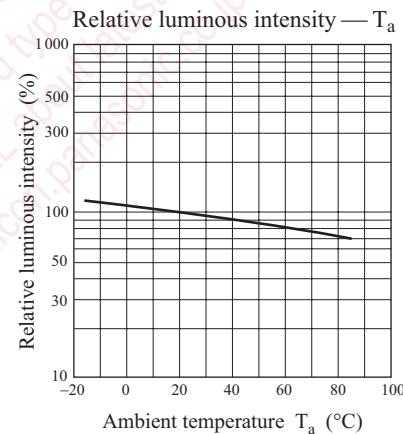
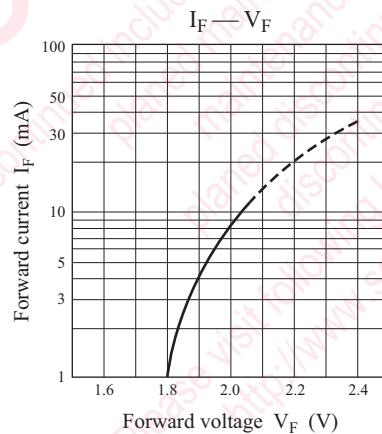
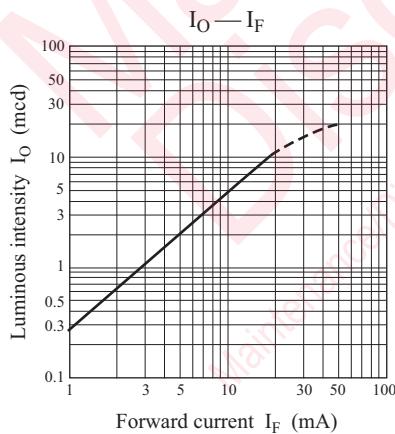
Note): The condition of  $I_{FP}$  is duty 10%, Pulse width 1 msec.

### ■ Lighting Color

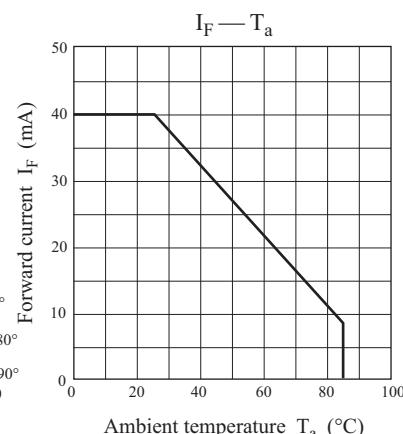
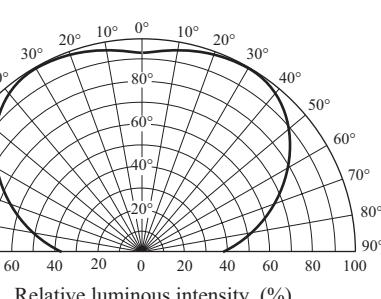
- Yellow Green

### ■ Electro-Optical Characteristics $T_a = 25^\circ\text{C}$

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Luminous intensity	$I_O$		1.8	5.0		mcd
Reverse current	$I_R$	$V_R = 4\text{ V}$			10	$\mu\text{A}$
Forward voltage	$V_F$	$I_F = 10\text{ mA}$		2.03	2.6	V
Peak emission wavelength	$\lambda_P$	$I_F = 10\text{ mA}$		565		nm
Spectral half band width	$\Delta\lambda$	$I_F = 10\text{ mA}$		30		nm

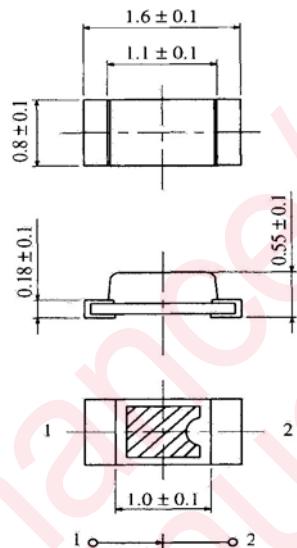


Directive characteristics



■ Package (Unit: mm)

**KLTFTN2K1200**



• Pin name

1: Anode

2: Cathode

Maintenance/Discontinued includes following four Product lifecycle stage.  
planed maintenance type  
maintenance type  
planed discontinued type  
discontinued type  
Please visit following URL about latest information.  
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